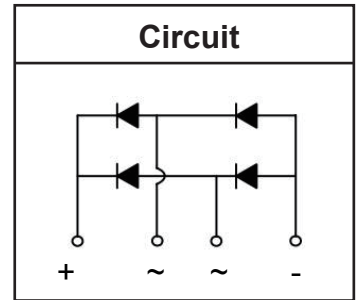
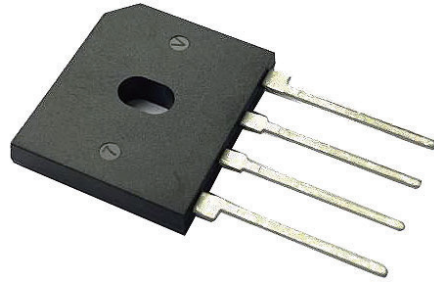


GBU0802 thru GBU0812

Feature

- Glass passivated die construction
- Ideal for printed circuit boards
- High surge current capability
- High temperature soldering guaranteed: 265°C /10 seconds, 0.375" (9.5mm) lead length, 5lbs. (2.3kg) tension



Mechanical Data

- Case: Molded plastic case
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026
- Polarity: Marked on Body
- Mounting Position: Any

Maximum value

Symbol	Parameter	Rating						Unit
		GBU0802	GBU0804	GBU0806	GBU0808	GBU0810	GBU0812	
VRRM	Reverse peak repetitive voltage	200	400	600	800	1000	1200	V
VRSM	Reverse peak non-repetitive voltage	300	500	700	900	1100	1300	V

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Symbol	Conditions	Rating	Unit
Id	Average forward output current sine wave ,R-load Tc =100°C	8	A
IFSM	Peak forward surge current single half sine-wave superimposed on rated load (JEDEC Method) 50Hz Tj=25°C	175	A
I ² t	Rating for fusing (t=1~10ms)	153	A ² S
Viso	A.C.50/60Hz;R.M.S.;1min	2000	V
Tj,Tstg	Operating Junction and storage temperature range	-40 to +150	°C
Ms	Mounting Torque (Recommended torque:0.65 N·m)	0.8	N·m
Wt	Approximate Weight	4	g

Electrical characteristics

Symbol	Conditions	Value	Unit
VFM	Maximum Forward Voltage per leg IFM =4A, Tj=25°C	1.0	V
IRRM	Maximum reverse current at rated blocking voltage per leg Tj=150°C	0.5	mA
Rth(j-c)	Maximum thermal resistance per (Junction to case)	per diode	10
		total	2.5

GBU0802 thru GBU0812

Performance Curves

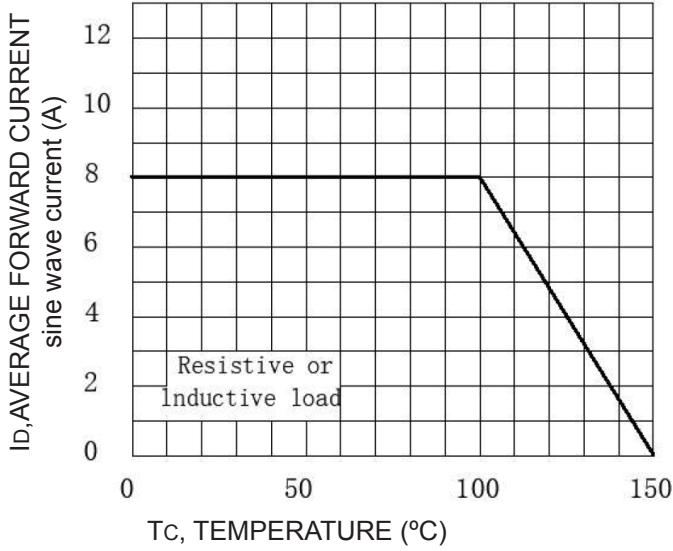


Fig.1 Forward Current Derating Curve

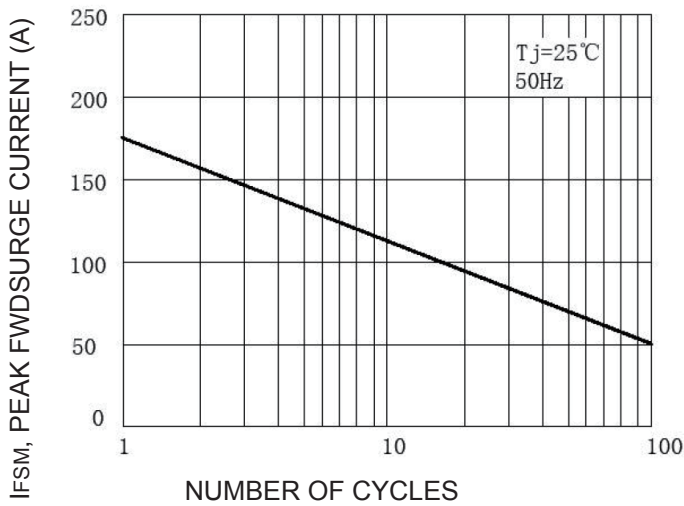


Fig.3 Max Non-Repetitive Surge Current

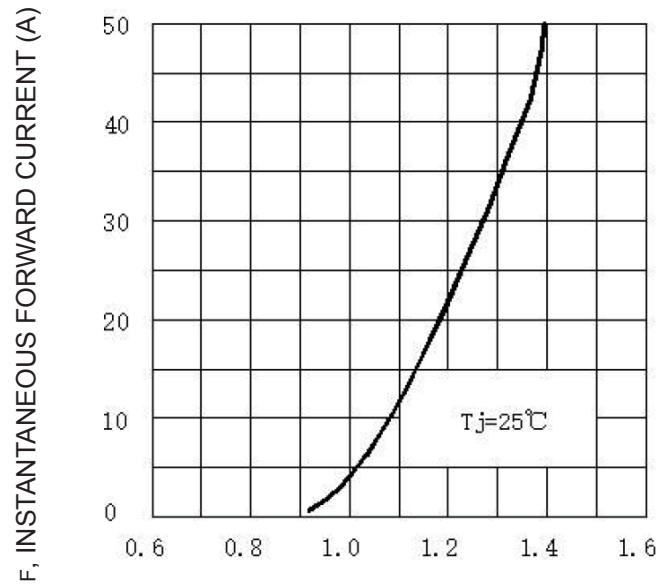


Fig.2 Maximum Forward Characteristics, per element

Outline

